

C28SOI_IO_ALLF_FRAMEKIT_EG_6U1X2T8XLB Release Notes and Known Problems and Solutions

1. Release Notes

1.1 Product Release Information

Table 1. Product Identification

Parameter	Description
Library Name	C28SOI_IO_ALLF_FRAMEKIT_EG_6U1X2T8XLB
Library Version	7.0
Library Type	IO Cells
Technology	CMOS028_FDSOI
DK Version	DK_cmos28FDSOI_AMS_6U1x_2T8x_LB 2.7.a-31

1.2 Impact of Product Release

For latest information, please refer to LYS (http://col2.cro.st.com/libyield).

1.3 Related Documentation

- C28SOI_IO_ALLF_FRAMEKIT_EG_7.0 Release Notes and Known Problems and Solutions
- C28SOI_IO_ALLF_FRAMEKIT_EG_7.0 User Manual



2. Changes with respect to all Previous Versions

2.1 Version 7.0

- A. This is the Final release.
- B. This package contains SIGNOFF GDS, CDL and SYNOPSYS LAYOUT, IODA.
- C. First BE release



3. Known Problems and Solutions of this release



This document is compatible for viewing with acroread 7.0 and later versions. If opened with a lower version of acroread, there might be some color display problem.



— DRC errors —

EMET.DEN.1 Corrected at chip level

EMET.DEN.2 Corrected at chip level

EMET.DEN.3 Corrected at chip level

EMET.DEN.4 Corrected at chip level

EMET.DEN.5 Corrected at chip level

EMET.DEN.6 Corrected at chip level

EMET.DEN.7 Corrected at chip level

EMET.DEN.8 Corrected at chip level

EMET.DEN.9 Corrected at chip level

EMET.DEN.10 Corrected at chip level

EMET.DEN.11 Corrected at chip level

EMET.DEN.12 Corrected at chip level

RX.DEN.1 Corrected by tiles

PC.DEN.1 Corrected by tiles

M1.DEN.1 Corrected by tiles

M2.DEN.1 Corrected by tiles

M3.DEN.1 Corrected by tiles

M4.DEN.1 Corrected by tiles

M5.DEN.1 Corrected at chip level

M6.DEN.1 Corrected at chip level

IA.DEN.1 Corrected at chip level

IB.DEN.1 Corrected at chip level

VV.DEN.2 Corrected by abutment

GR8x00_IA Corrected by abutment

GR8x01a_IA Corrected by abutment

GR601a_{M5} Corrected by abutment

GR601aSE_M5 Corrected by abutment

HYBRID.W.1 Corrected by abutment

GRB_N301 Corrected by abutment

GR3T02 Corrected by abutment

GR8x00_IB Corrected by abutment





— LVS errors ——

Different numbers of ports/nets/instances - FRAMEKIT_EX_SFPHY_EMPTYCELL_-EMPTYCELL_50U_2ROWS, FRAMEKIT_EX_SF_EMPTYCELL/VDDE/GNDE_40U_FC_-OUTER - Corrected by abutment

Nothing in layout - All examples with empty schematic - Corrected at chip level



— ERC errors ——

ERC1a - FRAMEKIT_EX_ANAF*, ESDHUB and FILLCEL_1G/1U examples - Corrected at chip level

ERC_PWTW_DIODE - All SF and SFPHY examples - Mkr LVS1 dg8 not added in SF/SFPHY frames because no more supported

SOFTCHECK error - FEEDTHROUGH, ESDHUB, *FILLCELL_1U_CL_LIN examples - Corrected by using SXCUT drawing or by abutment for thin cells



4. Contact Information

For more information about this product/IP/Library or any problems or suggestions, please contact HELPDESK (http://col2.cro.st.com/helpdesk).

Non-ST users, please contact the respective Customer Support.





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